

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bruce J. Freyman, et al. ✓ *st 8/A
JL
7-26-96*
 Assignee: Amkor Electronics, Inc.
 Title: MOLD RUNNER REMOVAL FROM A SUBSTRATE BASED
 PACKAGED ELECTRONIC DEVICE
 Serial No.: 08/214,339 / Filed: March 16, 1994 ✓
 Examiner: Decker, R. / Group Art Unit: 21 **RECEIVED**
 Attorney Docket No.: M-2556 US ✓
 JUL 23 1996

GROUP 2100

San Jose, California
 July 12, 1996

COMMISSIONER OF PATENTS AND TRADEMARKS
 Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed April 18, 1996,
 please amend the above-identified application as follows.

IN THE CLAIMS

Please cancel Claims 15-22.

Please amend Claims 1-14 as follows:

1. (AMENDED) A substrate-based packaged electronic device, comprising:

a substrate having first and second surfaces[,
 wherein:] ;

a degating region [is formed] on the first surface of the substrate;

a degating region material on the degating region;
 [and]

a structure for making external electrical connection from the substrate-based packaged electronic device [is formed] on the second surface of the substrate;

an electronic device attached to the first surface of the substrate, the electronic device being electrically connected to the structure for making external electrical connection; and

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